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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application of: Gene R. Anderson <i>et al.</i>	
Serial No.: 09/749,287	Group Art Unit: 2839
Filed: December 26, 2000	Examiner: Brian S. Webb
Title: <b>Process For Coupling Optical Elements To Optoelectronic Devices</b>	White & Case Docket No.: 1613370-0013

I hereby certify that this paper is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231, on December 2, 2002.

Christina Ishihara  
Name

December 2, 2002  
Date

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**RESPONSE TO JUNE 5, 2002 OFFICE ACTION**

Assistant Commissioner of Patents  
Washington, D.C. 20231

Sir:

In response to the Office Action mailed in June 5, 2002, Applicants respectfully request the Examiner to enter this reply.

**In the Specification:**

The specification has been amended as follows:

On page 27, lines 20-24:

In summary, the flexible printed circuit board 102 supports the main electrical components and elements of the optical module, such as the optoelectronic devices 106, driver or amplifier chip 108 and first ferrule 112, as well as providing bending freedom and stress relief to the optical module 100. The flexible printed circuit board 102 is attached to, and partially enclosed by, a housing, which is described below.

On page 35, lines 23-27: